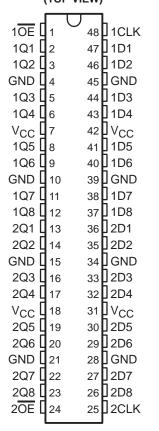
SCBS145L - MAY 1992 - REVISED APRIL 1999

- **Members of the Texas Instruments** Widebus™ Family
- State-of-the-Art Advanced BiCMOS Technology (ABT) Design for 3.3-V Operation and Low Static-Power Dissipation
- **Support Mixed-Mode Signal Operation** (5-V Input and Output Voltages With 3.3-V V_{CC})
- **Support Unregulated Battery Operation** Down to 2.7 V
- Typical V_{OLP} (Output Ground Bounce) $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_{A} = 25^{\circ}\text{C}$
- I_{off} and Power-Up 3-State Support Hot Insertion
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown **Resistors**
- Distributed V_{CC} and GND Pin Configuration **Minimizes High-Speed Switching Noise**
- Flow-Through Architecture Optimizes PCB Layout
- **ESD Protection Exceeds 2000 V Per** MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- **Package Options Include Plastic Shrink** Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages and 380-mil Fine-Pitch Ceramic Flat (WD) Package **Using 25-mil Center-to-Center Spacings**

SN54LVTH16374...WD PACKAGE SN74LVTH16374... DGG OR DL PACKAGE (TOP VIEW)



description

The 'LVTH16374 devices are 16-bit edge-triggered D-type flip-flops with 3-state outputs designed for low-voltage (3.3-V) V_{CC} operation, but with the capability to provide a TTL interface to a 5-V system environment. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

These devices can be used as two 8-bit flip-flops or one 16-bit flip-flop. On the positive transition of the clock (CLK), the Q outputs of the flip-flop take on the logic levels set up at the data (D) inputs.

A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.



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description (continued)

OE does not affect internal operations of the flip-flop. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

When V_{CC} is between 0 and 1.5 V, the devices are in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 1.5 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using I_{off} and power-up 3-state. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

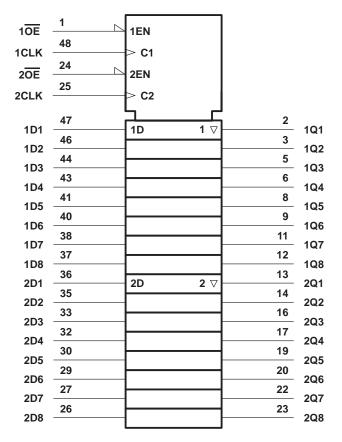
The SN54LVTH16374 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74LVTH16374 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE (each flip-flop)

	ОИТРИТ		
OE	CLK	D	Q
L	\uparrow	Н	Н
L	\uparrow	L	L
L	H or L	X	Q ₀
Н	Χ	Χ	Z

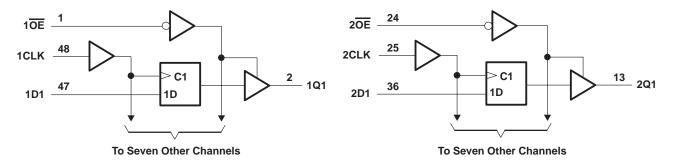


logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 4.6 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance	
or power-off state, V _O (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (see Note 1)	\cdot . -0.5 V to V _{CC} + 0.5 V
Current into any output in the low state, IO: SN54LVTH16374	96 mA
SN74LVTH16374	
Current into any output in the high state, I _O (see Note 2): SN54LVTH16374)	48 mA
SN74LVTH16374)	64 mA
Input clamp current, I_{IK} ($V_I < 0$)	
Output clamp current, I _{OK} (V _O < 0)	
Package thermal impedance, θ _{JA} (see Note 3): DGG package	89°C/W
DL package	94°C/W
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 - 2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Note 4)

			SN54LVTI	116374	SN74LVTI	UNIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage	2.7	3.6	2.7	3.6	V	
VIH	High-level input voltage		2		2		V
V _{IL}	Low-level input voltage		0.8		0.8	V	
VI	Input voltage		5.5		5.5	V	
ЮН	High-level output current		-24		-32	mA	
loL	Low-level output current			48		64	mA
Δt/Δv	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔVCC	Power-up ramp rate		200		200		μs/V
T _A	Operating free-air temperature		– 55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS			4LVTH16	374	SN7	4LVTH16	374	LINIT				
PAI	KAMETEK	lESI C	ONDITIONS	MIN	TYP†	MAX	MIN	TYP [†]	MAX	UNIT				
VIK		$V_{CC} = 2.7 \text{ V}, \qquad I_{I} = -18 \text{ mA}$				-1.2			-1.2	V				
Vall		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I _{OH} = -100 μA	V _{CC} -0	.2		V _{CC} -0	.2						
		$V_{CC} = 2.7 \text{ V},$	I _{OH} = -8 mA	2.4			2.4			V				
VOH		V _{CC} = 3 V	$I_{OH} = -24 \text{ mA}$	2				·						
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2]				
		V _{CC} = 2.7 V	I _{OL} = 100 μA			0.2			0.2					
		VCC = 2.7 V	I _{OL} = 24 mA			0.5			0.5					
VOL			I _{OL} = 16 mA			0.4			0.4	V				
VOL		V _{CC} = 3 V	I _{OL} = 32 mA			0.5			0.5	·				
		VCC = 3 V	$I_{OL} = 48 \text{ mA}$			0.55								
			I _{OL} = 64 mA					0.55						
		$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V _I = 5.5 V			10			10					
ΙΙ	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND		±1				±1	μΑ				
'		VCC = 3.6 V	VI = VCC			1			1	μι				
	Data inputs		V _I = 0			-5			- 5					
l _{off}	I_{Off} $V_{\text{CC}} = 0$,		V_I or $V_O = 0$ to 4.5 V						±100	μΑ				
		VCC = 3 V	V _I = 0.8 V	75			75							
l(hold)	Data inputs		V _I = 2 V	-75			-75			μΑ				
i(iloid)		$V_{CC} = 3.6 V^{\ddagger}$	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						500 -750	,				
lozh		$V_{CC} = 3.6 \text{ V},$	V _O = 3 V			5			5	μΑ				
lozL		$V_{CC} = 3.6 \text{ V},$	$V_0 = 0.5 V$			-5			– 5	μΑ				
I _{OZPU}		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$	0.5 V to 3 V,			±100*			±100	μΑ				
lozpd	OZPD $\frac{V_{CC} = 1.5 \text{ V to 0, V}_{O} = 0.8}{OE = \text{don't care}}$		0.5 V to 3 V,			±100*			±100	μА				
	V _{CC} = 3.6 V,	Outputs high	1	0.19		0.19		0.19						
Icc	Icc	$I_{O} = 0$,	Outputs low	5			5		mA					
		$V_I = V_{CC}$ or GND	Outputs disabled		0.19				0.19					
Δl _{CC} §	ΔI_{CC} $V_{CC} = 3 \text{ V to } 3.6 \text{ V, One}$ Other inputs at V_{CC} or C					0.2			0.2	mA				
Ci		V _I = 3 V or 0			3			3		pF				
Co	$V_O = 3 \text{ V or } 0$				9			9		pF				
		•				-								

^{*} On products compliant to MIL-PRF-38535, this parameter is not production tested.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

[§] This is the increase in supply current for each input that is at the specified TTL voltage level rather than VCC or GND.

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timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		SN54LVTH16374				SN74LVTH16374					
			V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		V _{CC} = 3.3 ± 0.3 V		V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			160		160		160		160	MHz
t _W	Pulse duration, CLK high or low		3		3		3		3		ns
t _{su}	Setup time, data before CLK↑	High or low	2.9		3.3		1.8		2		ns
th	Hold time, data after CLK↑	High or low	0.8		0.2		0.8		0.1		ns

switching characteristics over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see Figure 1)

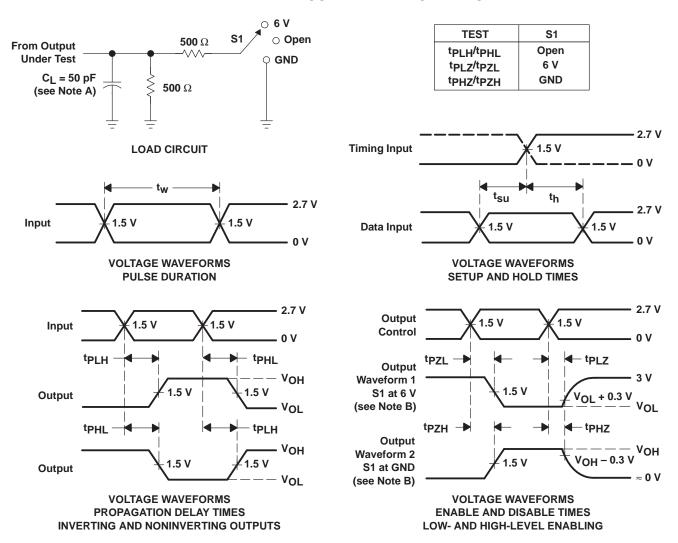
		SN54LVTH16374				SN74LVTH16374						
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = 3.3 V ± 0.3 V		V _{CC} = 2.7 V		VCC = 3.3 V ± 0.3 V			V _{CC} = 2.7 V		UNIT
			MIN	MAX	MIN	MAX	MIN	TYP†	MAX	MIN	MAX	
f _{max}			160		160		160			160		MHz
t _{PLH}	CLK	Q	1.4	5.6		6.2	1.9	3	4.5		5.2	ns
t _{PHL}		Q	1.7	4.8		5	2.1	2.9	4		4.2	115
^t PZH	ŌĒ	Q	1	5.6		6.4	1.5	2.8	4.5		5.4	ns
t _{PZL}	OE	Q .	1.4	5.5		6.2	1.5	2.8	4.4		5	115
^t PHZ	ŌĒ	Q	1	6.4		6.9	2.4	3.5	5		5.4	ns
^t PLZ			1.7	5		5.2	2	3.2	4.6		4.8	115
^t sk(o)									0.5			ns

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



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PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2.5 \ ns$, $t_f \leq 2.5 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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